

Product Change Notification - GBNG-06HGKA436

Date:

30 Aug 2019

Product Category:

Temperature Sensors

Affected CPNs:

Notification subject:

CCB 3738 and 3738.001 Final Notice: Qualification of NSEB as a new assembly site for selected SMSC products of the 0.18 um Global Foundries wafer technology available in 10L MSOP (3x3mm) package.

Notification text:
PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of NSEB as a new assembly site for selected SMSC products of the 0.18 um Global Foundries wafer technology available in 10L MSOP (3x3mm) package.

Pre Change:

Assembled at OSE using EN4900G die attach, CEL-9200HF mold compound and Ring Ag lead frame surface material.

Post Change:

Assembled at NSEB using 8200T die attach, G600 mold compound and Full Ag lead frame surface material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Orient Semiconductor Electronics, Ltd (OSE)	UTAC Thai Limited (UTL-1) LTD. (NSEB)
Wire material	Au	Au
Die attach material	EN4900G	8200T
Molding compound material	CEL-9200HF	G600
Lead frame material	C7025	C7025
Lead frame paddle surface	Ring Ag	Full Ag
	<i>See attachment for the comparison</i>	

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying NSEB as a new assembly site.

Change Implementation Status:

In Progress



Estimated First Ship Date:

September 30, 2019 (date code: 1940)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

	April 2019					>	August 2019					September 2019				
Workweek	14	15	16	17	18		31	32	33	34	35	36	37	38	39	40
Initial PCN Issue Date	X															
Qual Report Availability											X					
Final PCN Issue Date											X					
Estimated Implementation Date																X

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

April 01, 2019: Issued initial notification.

August 30, 2019: Issued final notification. Attached the qualification report and added estimated first ship date by September 30, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_GBNG-06HGKA436_Qual_report.pdf](#)
- [Ring Ag vs Full Ag Plating.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

EMC1046-1-AIZL-TR
EMC1046-6-AIZL-TR
EMC1047-1-AIZL-TR
EMC1047-2-AIZL-TR
EMC1073-1-AIZL-TR
EMC1073-A-AIZL-TR
EMC1074-1-AIZL-TR
EMC1074-A-AIZL-TR
EMC1403-1-AIZL-TR
EMC1403-2-AIZL-TR
EMC1403-4-AIZL-TR
EMC1404-1-AIZL-TR
EMC1404-2-AIZL-TR
EMC1404-3-AIZL-TR
EMC1413-1-AIZL-TR
EMC1413-A-AIZL-TR
EMC1414-1-AIZL-TR
EMC1414-3-AIZL-TR
EMC1414-A-AIZL-TR
EMC1423-1-AIZL-TR
EMC1424-1-AIZL-TR